IN THE CLAIMS

Claims 16-25 were previously canceled without prejudice as being drawn to a non-elected invention.

Claim 27 was previously canceled without prejudice.

Please amend claims 1 and 26.

Please enter the pending claims as follows:

1. (Currently Amended) A device having Input/Output (I/O) connections ~~to a package or board~~ comprising:

a bond pad;

a passivation layer disposed over said bond pad;

vias disposed in said passivation layer to uncover ~~over~~ said bond pad;

a BLM disposed over said vias, said BLM split into two or more segments, said segments in close proximity to each other, said segments separated by a gap, said segments connected to said bond pad; and

a bump disposed directly on said segments and in said vias.

2. (Previously Presented) The device of claim 1 wherein said bump comprises a Lead-Tin (Pb-Sn) solder.

3. (Previously Presented) The device of claim 1 wherein said bump is free of Lead (Pb).

4. (Previously Presented) The device of claim 1 wherein said bump comprises a Tin-Silver-Copper (Sn-Ag-Cu) ternary alloy.

5. (Previously Presented) The device of claim 1 wherein said bump comprises an Electrically Conductive Adhesive (ECA).

6. (Original) The device of claim 1 wherein said BLM provides a diffusion barrier to metals.

7. (Original) The device of claim 1 wherein said BLM comprises a lower layer and an upper layer.

8. (Original) The device of claim 7 wherein said lower layer comprises Titanium (Ti) with a thickness of about 200 to 1500 Angstroms.

9. (Original) The device of claim 7 wherein said upper layer comprises Nickel-Vanadium (Ni-V) with a thickness of about 1000 to 8000 Angstroms.

10. (Original) The device of claim 1 wherein said segments comprise a substantially polygonal layout.

11. (Previously Presented) The device of claim 1 wherein each of said segments is electrically connected to two or more of said vias.

12. (Original) The device of claim 11, wherein said vias are laterally offset from a center of said bump to which they are is electrically connected.

13. (Original) The device of claim 11 wherein said vias comprise a substantially polygonal layout.

14. (Previously Presented) The device of claim 1, further comprising another bond pad, wherein each of said segments is electrically connected to said bond pad and said another bond pad.

15. (Previously Presented) The device of claim 14 wherein said bond pad and said another bond pad are laterally offset from a center of said bump to which they are electrically connected.

16. – 25. (Canceled)

26. (Currently Amended) A device having I/O connections to a package or board comprising:

vias;

a bond pad disposed over said vias, said bond pad having two or more segments, said segments having the same shape, wherein each of said segments is electrically connected to two or more of said vias, and

a wire lead attached directly to said segments.

27. (Canceled)

28. (Previously Presented) The device of claim 26 further comprising lines, wherein each of said segments is electrically connected to two or more of said lines.